nexperia

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier		User Part Number						
Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		BAT960 Part Description						
								Nexperia DHAM Schottky
		SMD package						
		Test Conditions	Duration	# Lots	# Quantity	# Rejects		
			TEST					
	Pre- and Post-Stress							
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below		
		JESD22-A113						
		Bake Tamb = 125 °C	24 hours					
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours					
# A1	Preconditioning	Reflow soldering	3 cycles	810	58300	0		
		MIL-STD-750-1						
	HTRB	M1038 Method A						
	High Temperature Reverse	Tj = Tjmax, Vr = 100% of max. datasheet						
# B1	Bias	reverse voltage ^[1]	1000 hours	116	9280	0		
	тс	150000 4104						
	Temperature Cycling	JESD22-A104 -65 °C to Tjmax, not to exceed 150°C	1000	170	12600	0		
# A4	Temperature Cycling		1000 cycles	170	13600	0		
	AC	JESD22-A102						
	AL Autoclave	Tamb = 121 °C, RH = 100 % Pressure = 205 kPa (29.7 psia)	0.5.1	170	12600			
# A3 alt	Autoclave	riessure – 203 kra (23.7 psia)	96 hours	170	13600	0		
	H3TRB	JESD22-A101						
	H31KB High Humidity High	Tamb = $85 ^{\circ}$ C, RH = 85% , VR = 80% of						
# A2 alt		rated reverse voltage ^{[1], [2]}	1000 hours	170	13600	0		
# AZ alt			1000 Hours	170	13000	U		
	IOL	MIL-STD-750 Method 1037						
4 AF	Intermittent Operating Life	ton = toff, devices powered to insure ΔT_j = 100 °C for 15000 cycles	1000 hours	170	12600	0		
# A5	Internittent Operating Life		1000 hours	170	13600	0		
	RSH	JESD22-A111						
# C8	Resistance to Solder Heat		10 s	130	3900	0		
# C8	SD	200 0 - 5 0	10.2	130	2900	0		
	Solderability	J-STD-002		262	2620	0		
	•	des have to be considered (thermal runaway).		363	3630	0		

[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia DHAM	Schottky	9280	0	0.46	2.19E+09
010/01	SCHULKY	9280	0	0:46	2.192+09

© 2022 Nexperia B.V.

All information hereunder is per Nexperia's best knowledge. This document does not provide for any representation or warranty express or implied by Nexperia. In case Nexperia has tested the product, this documentation reflects the outcome of the analysis of the actually tested parts only.

nexperia.com